

L Number	Hits	Search Text	DB	Time stamp
-	2	fritting near phenomenon	USPAT; US-PGPUB	2003/08/26 11:30
-	334	324/756-757.ccls.	USPAT; US-PGPUB	2003/03/04 18:32
-	100	324/756-757.ccls. and heat\$	USPAT; US-PGPUB	2003/03/04 17:02
-	3	324/756-757.ccls.	USOCR	2003/03/04 17:01
-	2	324/756-757.ccls. and heat\$	EPO; JPO; DERWENT; IBM_TDB	2003/03/04 17:02
-	49	(324/756-757.ccls. and heat\$) and oxide\$	USPAT; US-PGPUB	2003/03/04 17:13
-	6	(324/756-757.ccls. and heat\$) and oxide\$ same heat	USPAT; US-PGPUB	2003/03/04 17:14
-	4	(324/756-757.ccls. and heat\$) and oxide\$ with heat	USPAT; US-PGPUB	2003/03/04 17:46
-	1	6057694.URPN.	USPAT	2003/03/04 17:19
-	2	("5739052" "5861634").PN.	USPAT	2003/03/04 17:20
-	3954	removing near oxide\$	USPAT; US-PGPUB	2003/03/04 18:20
-	9720	removing near2 oxide\$	USPAT; US-PGPUB	2003/03/04 18:28
-	8329	removing near2 oxide\$	EPO; JPO; DERWENT; IBM_TDB	2003/03/04 18:21
-	1484	removing near2 oxide\$	USOCR	2003/03/04 17:48
-	173	(removing near2 oxide\$) and (wafer chip)	USOCR	2003/03/04 18:20
-	61	((removing near2 oxide\$) and (wafer chip)) and heat	USOCR	2003/03/04 17:49
-	3	((removing near2 oxide\$) and (wafer chip)) and heat) and pad	USOCR	2003/03/04 17:49
-	46	(removing near2 oxide\$) and ((wafer chip) same heat)	USOCR	2003/03/04 17:51
-	9	(removing near2 oxide\$) and ((wafer chip) with heat)	USOCR	2003/03/04 17:51
-	11	3206339.URPN.	USPAT	2003/03/04 17:59
-	0	(removing near2 oxide\$) and ((wafer chip) near heat)	USOCR	2003/03/04 18:20
-	11	removing near oxide\$ near2 heat	USPAT; US-PGPUB	2003/03/04 18:21
-	12	removing near2 oxide\$ near heat	EPO; JPO; DERWENT; IBM_TDB	2003/03/04 18:23
-	9	removing near2 oxide\$ near heat	USPAT; US-PGPUB	2003/03/04 18:28
-	239	324/756-757.ccls.	EPO; JPO; DERWENT; IBM_TDB	2003/03/04 18:31
-	0	324/756-757.ccls. and oxide same heat	EPO; JPO; DERWENT; IBM_TDB	2003/03/04 18:31
-	0	324/756-757.ccls. and oxide and heat	EPO; JPO; DERWENT; IBM_TDB	2003/03/04 18:31
-	40	324/756-757.ccls. and oxide and heat	USPAT; US-PGPUB	2003/03/04 18:34
-	649	439/\$.ccls. and oxide and heat	USPAT; US-PGPUB	2003/03/04 18:34
-	22	439/\$.ccls. and remov\$ same oxide same heat	USPAT; US-PGPUB	2003/03/04 18:48
-	99	oxide same heat\$ near2 pad	USPAT; US-PGPUB	2003/03/04 18:50

